**PCB SPECS**

THICKNESS : 1.2 MM / 0.047 IN
1/2 OZ CU THICKNESS: 0.7 MILS
1.0 OZ CU THICKNESS: 1.4 MILS

IMPEDANCE : 50 OHMS +/- 10%
DIELECTRIC: FR-4
LAYER COUNT: 10
SIGNAL TRACE WIDTH: 4 MILS
SIGNAL TRACE SPACING: 4 MILS
PREPREG THICKNESS: 2-3 MILS

IMPEDANCE: 50 OHMS +/- 10%
DIELECTRIC: FR-4
SIGNAL TRACE WIDTH: 4 MILS
SIGNAL TRACE SPACING: 4 MILS
PREPREG THICKNESS: 2-3 MILS

SEE PCB CAD FILES FOR MORE SPECIFIC INFO.

**BOARD STACK-UP AND CONSTRUCTION**

1. PREPREG (3 MIL)
2. PREPREG (3 MIL)
3. CORE (5 MIL)
4. PREPREG (3 MIL)
5. CORE (5 MIL)
6. PREPREG (3 MIL)
7. CORE (5 MIL)
8. PREPREG (3 MIL)
9. PREPREG (3 MIL)
10. PREPREG (5 MIL)

**BOARD HOLES**

CHASSIS MOUNTS

ASICS HEATSINK MOUNTS

GROUND VIAS

I/O AREA

INVERTER

MECH. HOLES

**BOARD INFORMATION**

PROPERTY OF APPLE COMPUTER, INC. THE POSSESSOR TO MAINTAIN THE DOCUMENT IN CONFIDENCE

NOTICE OF PROPRIETARY PROPERTY

SIZE

SCALE

DRAWING NUMBER

SHT

OF

D

B

A

C

D
SEL = LOW; HOST = B PORT; A PORT = 1000OHM TO GND
SEL = HIGH; HOST = A PORT; B PORT = 1000OHM TO GND
Place these 2.5V Decoupling Caps near the Edge of +2.5V_MAIN and +2.5V_INTREPID split.
LMU/RIGHT SENSOR CONNECTOR

LEFT LIGHT SENSOR CONNECTOR

DEBUG HELPERS

SLEEP LED

TOP CONTACT ZIP KEYBOARD CONN

TRACKPAD/PWR BTN CONN

KEYBOARD/PULLUPS